



## Material Content Data Sheet



<b>Sales Product Name</b>		IPB80P04P4L-08		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA000892290						
<b>Package</b>		PG-TO263-3-2		<b>Weight*</b>		1557.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.074	0.13	0.13	1332	1332
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.52	19.55	195179	195433
	non noble metal	aluminium	7429-90-5	5.357	0.34	0.34	3439	3439
wire	non noble metal	aluminium	7429-90-5	5.357	0.34	0.34	3439	3439
encapsulation	organic material	carbon black	1333-86-4	10.283	0.66		6602	
	plastics	epoxy resin	-	113.115	7.26		72618	
	inorganic material	silicondioxide	60676-86-0	562.148	36.10	44.02	360887	440107
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6199	6199
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	147	148
solder	non noble metal	tin	7440-31-5	0.040	0.00		26	
	noble metal	silver	7440-22-4	0.050	0.00		32	
	non noble metal	lead	7439-92-1	1.923	0.12	0.12	1235	1293
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		106	
	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.16	35.21	351591	352049
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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